



Material Content Data Sheet



Sales Product Name	TLD5098EL			Issued		28. August 2013		
MA#	MA000982098							
Package	PG-SSOP-14-3			Weight*		83.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.131	2.56	2.56	25601	25601
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.689	0.83		8276	
	non noble metal	copper	7440-50-8	27.978	33.60	34.48	336046	344839
wire	noble metal	gold	7440-57-5	0.395	0.47	0.47	4739	4739
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1190	
	plastics	epoxy resin	-	4.558	5.48		54752	
	inorganic material	silicondioxide	60676-86-0	44.890	53.92	59.52	539186	595128
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11724	11724
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9220	9220
glue	plastics	epoxy resin	-	0.182	0.22		2187	
	noble metal	silver	7440-22-4	0.546	0.66	0.88	6562	8749
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com